

ABSTRACT

A new method and assembly ~~is~~ are provided for anchoring the heat spreader of a PBGA package to the substrate thereof. ~~Anchor features are made as~~ part of the PBGA package, ~~these package.~~ These anchor features are provided over the surface of the substrate of the PBGA package. The anchor features align with openings created in the heat spreader stand-off, thus allowing for quick and reliable positioning and anchoring of the heat spreader over the surface of the substrate of the package.